

HEXFRED® Ultrafast Soft Recovery Diode, 280 A



| PRIMARY CHARACTERISTICS | | | | |
|--------------------------------------|---------------------------|--|--|--|
| I _{F(AV)} | 280 A | | | |
| V _R | 600 V | | | |
| I _{F(DC)} at T _C | 149 A at 100 °C | | | |
| Package | TO-244 | | | |
| Circuit configuration | Two diodes common cathode | | | |

FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165



- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- · Reduced RFI and EMI
- Reduced snubbing

DESCRIPTION / APPLICATIONS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dI_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

| ABSOLUTE MAXIMUM RATINGS | | | | | |
|--|-----------------------------------|---|-------------|-------|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS | |
| Cathode to anode voltage | V _R | | 600 | V | |
| Continuous forward current | | T _C = 25 °C | 292 | | |
| Continuous forward current | I _F | T _C = 100 °C | 149 | Α | |
| Single pulse forward current | I _{FSM} | Limited by junction temperature | 600 | | |
| Non-repetitive avalanche energy | E _{AS} | $L = 100 \mu H$, duty cycle limited by maximum T_J | 2.2 | mJ | |
| Maximum power dissipation P _D | | T _C = 25 °C | 657 | w | |
| | | T _C = 100 °C | 263 | VV | |
| Operating junction and storage temperature range | T _J , T _{Stg} | | -55 to +150 | °C | |

| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | |
|--|-----------------|---|------------|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNITS |
| Cathode to anode breakdown voltage | V _{BR} | I _R = 100 μA | | 600 | - | - | |
| | | I _F = 105 A | | - | 1.33 | 1.8 | V |
| Maximum forward voltage | V_{FM} | I _F = 210 A | See fig. 1 | - | 1.53 | 2.1 | |
| | | I _F = 105 A, T _J = 125 °C | | - | 1.22 | 1.64 | |
| Maximum reverse leakage current | I _{RM} | T _J = 125 °C, V _R = 600 V | See fig. 2 | - | 2.4 | 8 | mA |
| Junction capacitance | C _T | V _R = 200 V | See fig. 3 | - | 280 | 400 | pF |
| Series inductance | L _S | From top of terminal hole to mounting plane - 5.0 | | 5.0 | =. | nΗ | |



| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | | |
|---|--------------------------|--|--|------|------|------|-------|------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time | | $I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$ | | - | 39 | - | | |
| See fig. 5 | t _{rr} | T _J = 25 °C | | - | 92 | 140 | ns | |
| | | T _J = 125 °C | | - | 180 | 270 | | |
| Peak recovery current | , legge | | T _J = 25 °C | | - | 9.3 | 17 | ۸ |
| See fig. 6 | | T _J = 125 °C | I _F = 105 A dI _F /dt = 200 A/μs | - | 16 | 30 | Α Α | |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C | $V_{R} = 200 \text{ V}$ | - | 490 | 1200 | nC | |
| See fig. 7 | | T _J = 125 °C | | - | 1400 | 4000 | 110 | |
| Peak rate of recovery current | طا (ط∔ | dl /d+ | T _J = 25 °C | | - | 290 | - | A/µs |
| See fig. 8 | dI _{(rec)M} /dt | T _J = 125 °C | | - | 200 | - | AνμS | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | |
|---|-------------|---|-------------|------|-----------------|---------------------|
| PARAMETER Maximum junction and storage temperature range | | SYMBOL T _J , T _{Stg} | MIN. -55 | TYP. | MAX. 150 | UNITS °C |
| | | | | | | |
| Thermal resistance, junction to case | per module | - R _{thJC} | - | - | 0.095 | |
| Typical thermal resistance, case to heatsink | | R _{thCS} | - | 0.10 | - | 1000 |
| Weight | | | - | 68 | - | g |
| | | | - | 2.4 | - | oz. |
| Marina tarana (1) | | | 30 (3.4) | - | 40 (4.6) | |
| Mounting torque (1) | center hole | | 12 (1.4) | - | 18 (2.1) | lbf ⋅ in (N ⋅ m) |
| Terminal torque | | | 30 (3.4) | = | 40 (4.6) |] ('1 ''') |
| Vertical pull | | | - | = | 80 | lbf ⋅ in |
| 2" lever pull | | | - | - | 35 | IDI · IN |

Note

⁽¹⁾ Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached.

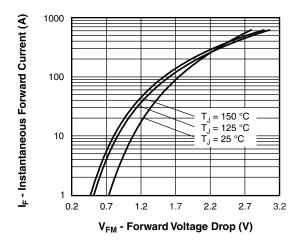


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

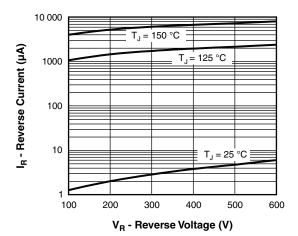


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

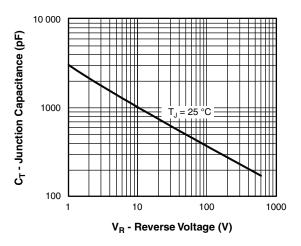


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

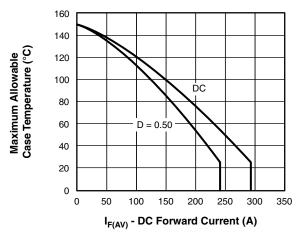


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

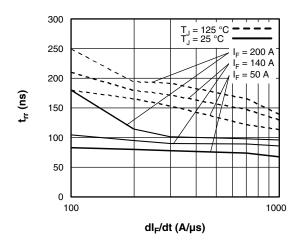


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt (Per Leg)

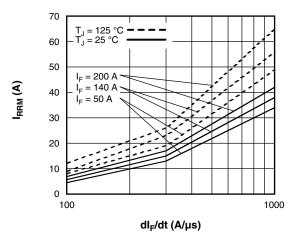


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

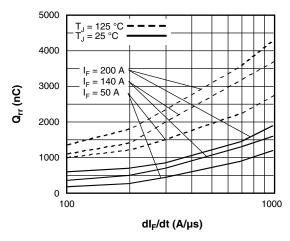


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

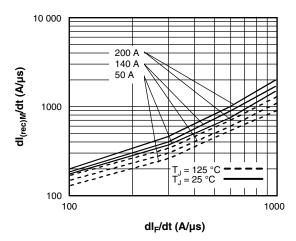


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)

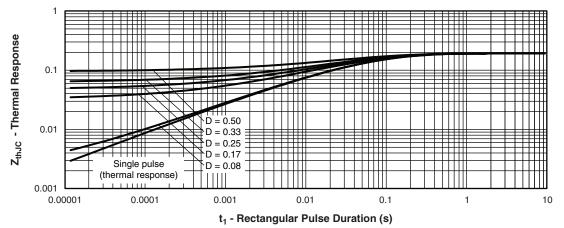


Fig. 9 - Maximum Thermal Impedance ZthJC Characteristics (Per Leg)

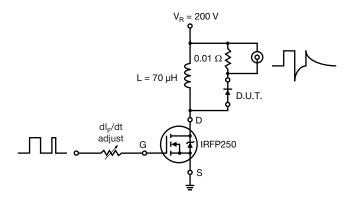
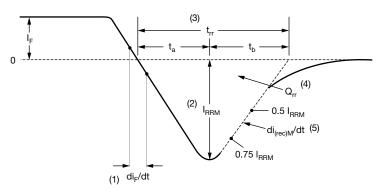


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{rr}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions



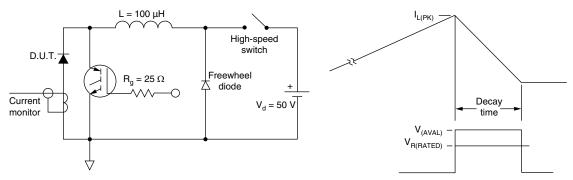
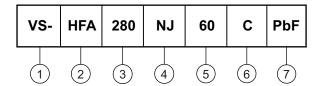


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

Device code



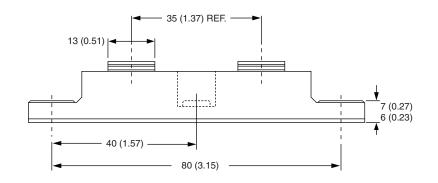
- 1 Vishay Semiconductors product
- 2 HEXFRED® family, electron irradiated
- 3 Average current rating
- **4** NJ = TO-224
- 5 Voltage rating (600 V)
- 6 C = two diodes common cathode
- 7 Lead (Pb)-free

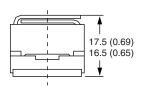
| LINKS TO RELATED DOCUMENTS | | | | |
|----------------------------|--------------------------|--|--|--|
| Dimensions | www.vishay.com/doc?95021 | | | |

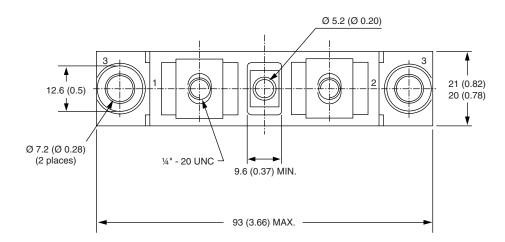


TO-244

DIMENSIONS in millimeters (inches)









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